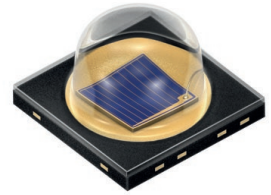


SFH 4725AS

OSLON® Black

OSLON Black Series (940 nm) - 80°



Applications

- Access Control (IRIS/Vein Scan, Face Recognition)
- CCTV Surveillance
- Eye Tracking
- Industrial Automation (Machine Controls, Light Barriers, Vision Controls)
- Safety and Security, CCTV

Features:

- Package: clear silicone
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- IR lightsource with high efficiency
- Double stack emitter
- Low thermal resistance (Max. 9 K/W)
- Centroid wavelength 940 nm
- Optimized for high brightness DC operation

Ordering Information

| Type | Radiant intensity ¹⁾²⁾ $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$ I_e | Radiant intensity ¹⁾ typ. $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$ I_e | Ordering Code |
|----------------|--|--|---------------|
| SFH 4725AS | 560 ... 1120 mW/sr | 900 mW/sr | Q65112A0782 |
| SFH 4725AS R33 | 560 ... 1120 mW/sr | 900 mW/sr | Q65113A3208 |

Maximum Ratings

$T_A = 25\text{ °C}$

| Parameter | Symbol | | Values |
|--|-----------|------|---------|
| Operating temperature | T_{op} | min. | -40 °C |
| | | max. | 125 °C |
| Storage temperature | T_{stg} | min. | -40 °C |
| | | max. | 125 °C |
| Junction temperature | T_j | max. | 145 °C |
| Forward current | I_F | max. | 1500 mA |
| Surge current $t_p \leq 800\ \mu\text{s}; D = 0.005$ | I_{FSM} | max. | 3 A |
| Reverse current ³⁾ | I_R | max. | 200 mA |
| Power consumption | P_{tot} | max. | 5.4 W |
| ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2) | V_{ESD} | max. | 2 kV |

For the forward current and power consumption please see “maximum permissible forward current” diagram

Characteristics

$I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$; $T_A = 25 \text{ °C}$

| Parameter | Symbol | | Values |
|---|-----------------------------|--------------|------------------------|
| Peak wavelength | λ_{peak} | typ. | 950 nm |
| Centroid wavelength | $\lambda_{\text{centroid}}$ | typ. | 940 nm |
| Spectral bandwidth at 50% $I_{\text{rel,max}}$ (FWHM) | $\Delta\lambda$ | typ. | 37 nm |
| Half angle | φ | typ. | 40 ° |
| Dimensions of active chip area | L x W | typ. | 1 x 1 mm x mm |
| Rise time (10% / 90%) $I_F = 3 \text{ A}$; $R_L = 50 \text{ }\Omega$ | t_r | typ. | 12 ns |
| Fall time (10% / 90%) $I_F = 3 \text{ A}$; $R_L = 50 \text{ }\Omega$ | t_f | typ. | 15 ns |
| Forward voltage ⁴⁾ | V_F | typ. max. | 2.9 V 3.4 V |
| Forward voltage ⁴⁾ $I_F = 1.5 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$ | V_F | typ. max. | 3.05 V 3.6 V |
| Forward voltage ⁴⁾ $I_F = 3 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$ | V_F | typ. max. | 3.5 V 4.2 V |
| Reverse voltage ³⁾ $I_R = 20 \text{ mA}$ | V_R | max. | 1.2 V |
| Reverse voltage (ESD device) ³⁾ | $V_{\text{RES D}}$ | min. | 5 V |
| Radiant intensity ¹⁾ $I_F = 1.5 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$ | I_e | typ. | 1350 mW/sr |
| Total radiant flux ⁵⁾ $I_F = 1 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$ | Φ_e | typ. | 1580 mW |
| Total radiant flux ⁵⁾ $I_F = 1.5 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$ | Φ_e | typ. | 2350 mW |
| Temperature coefficient of voltage | TC_V | typ. | -2 mV / K |
| Temperature coefficient of brightness | TC_I | typ. | -0.3 % / K |
| Temperature coefficient of wavelength | TC_λ | typ. | 0.3 nm / K |
| Thermal resistance junction solder point real ⁶⁾ | $R_{\text{thJS real}}$ | typ. max. | 5.5 K / W 9.0 K / W |

Brightness Groups

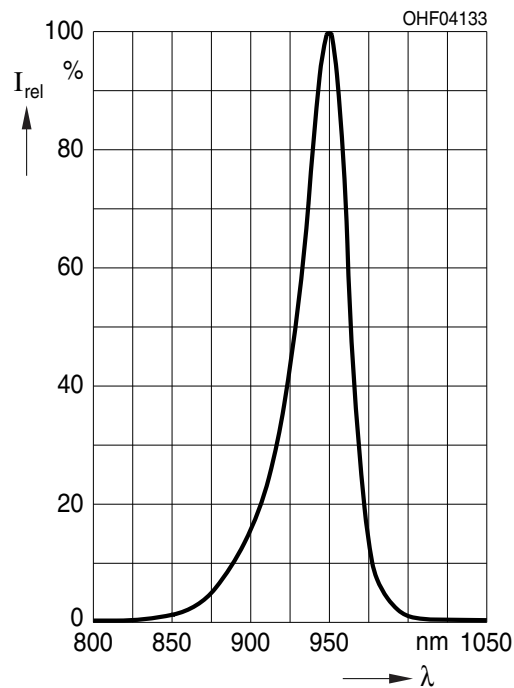
$T_A = 25\text{ °C}$

| Group | Radiant intensity ¹⁾²⁾ $I_F = 1000\text{ mA}; t_p = 10\text{ ms}$ min. I_e | Radiant intensity ¹⁾²⁾ $I_F = 1000\text{ mA}; t_p = 10\text{ ms}$ max. I_e |
|-------|--|--|
| | DB | 560 mW/sr |
| EA | 710 mW/sr | 900 mW/sr |
| EB | 900 mW/sr | 1120 mW/sr |

Only one group in one packing unit (variation lower 1.6:1).

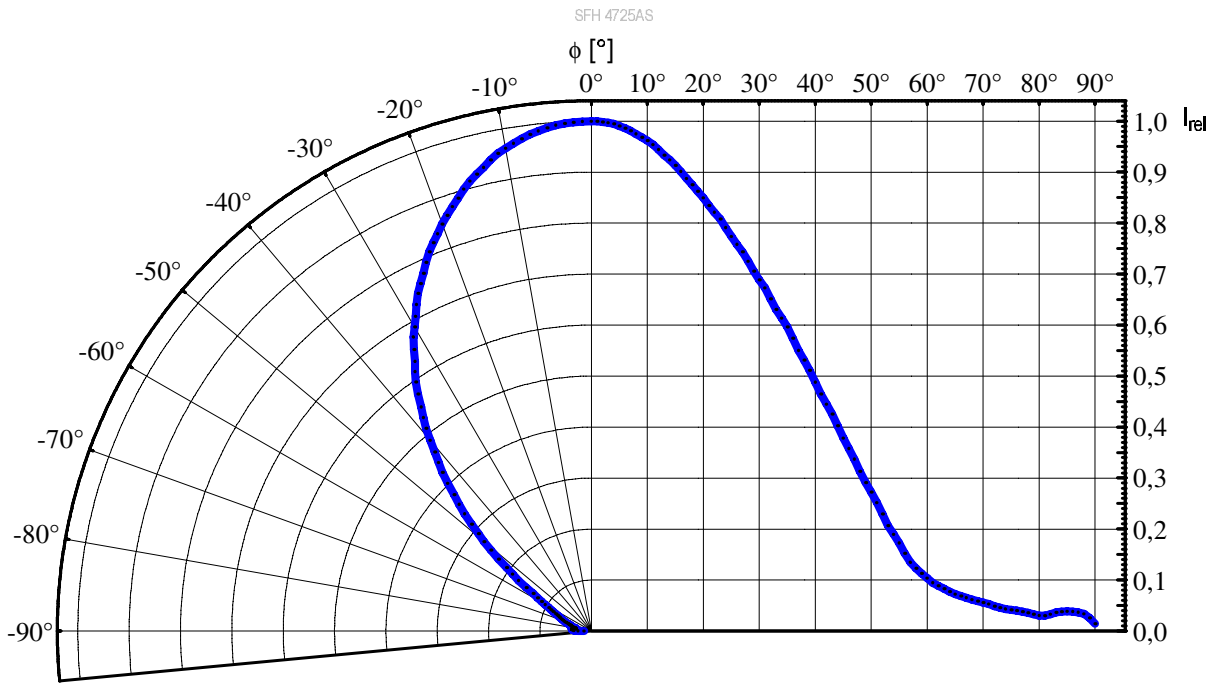
Relative Spectral Emission ^{7), 8)}

$I_{e,rel} = f(\lambda); I_F = 1000\text{ mA}; t_p = 10\text{ ms}$



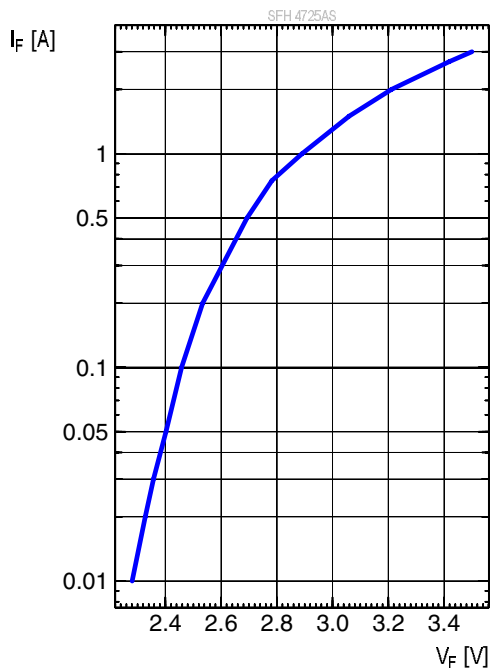
Radiation Characteristics (7), (8)

$I_{e,rel} = f(\varphi)$



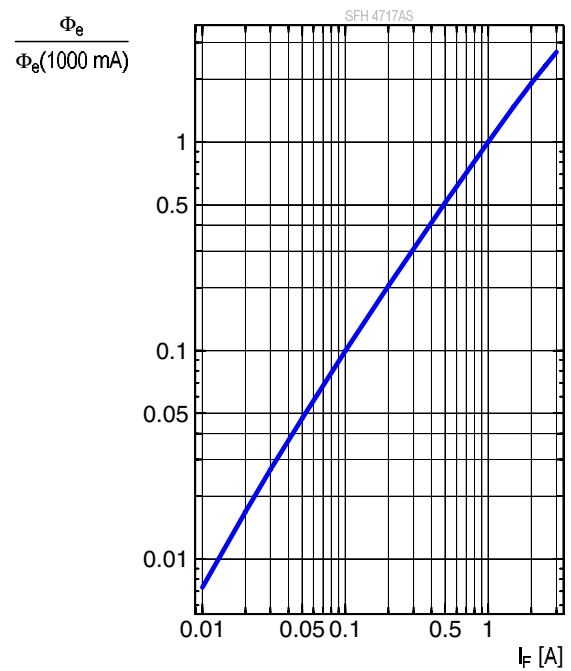
Forward current (7), (8)

$I_F = f(V_F)$; single pulse; $t_p = 100 \mu s$



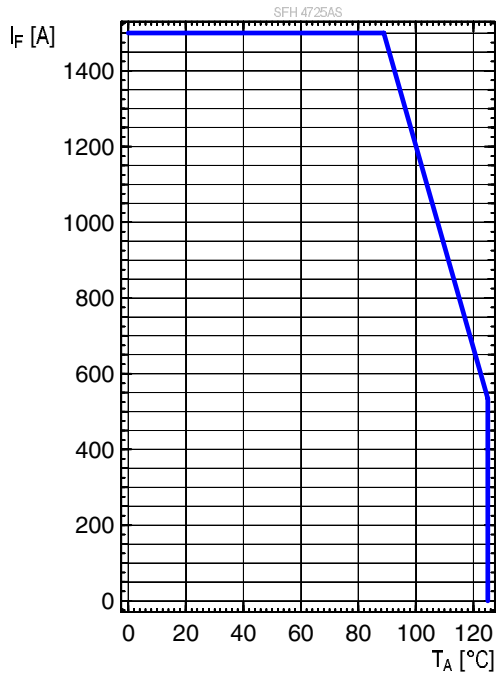
Relative Total Radiant Flux (7), (8)

$\Phi_e / \Phi_e(1000mA) = f(I_F)$; single pulse; $t_p = 100 \mu s$



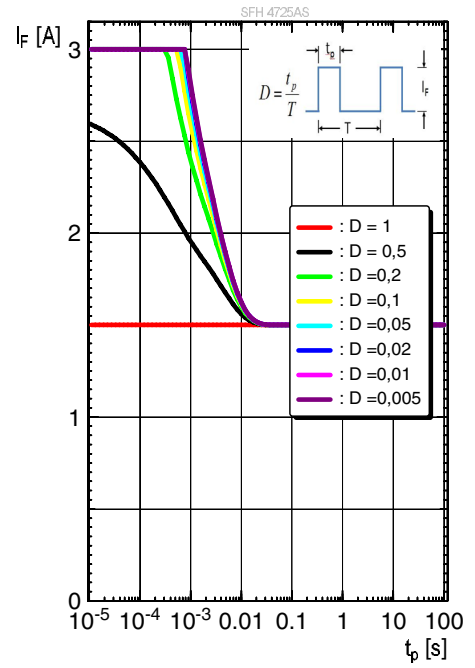
Max. Permissible Forward Current

$$I_{F,max} = f(T_S); R_{th_{js}} = 9K / W$$

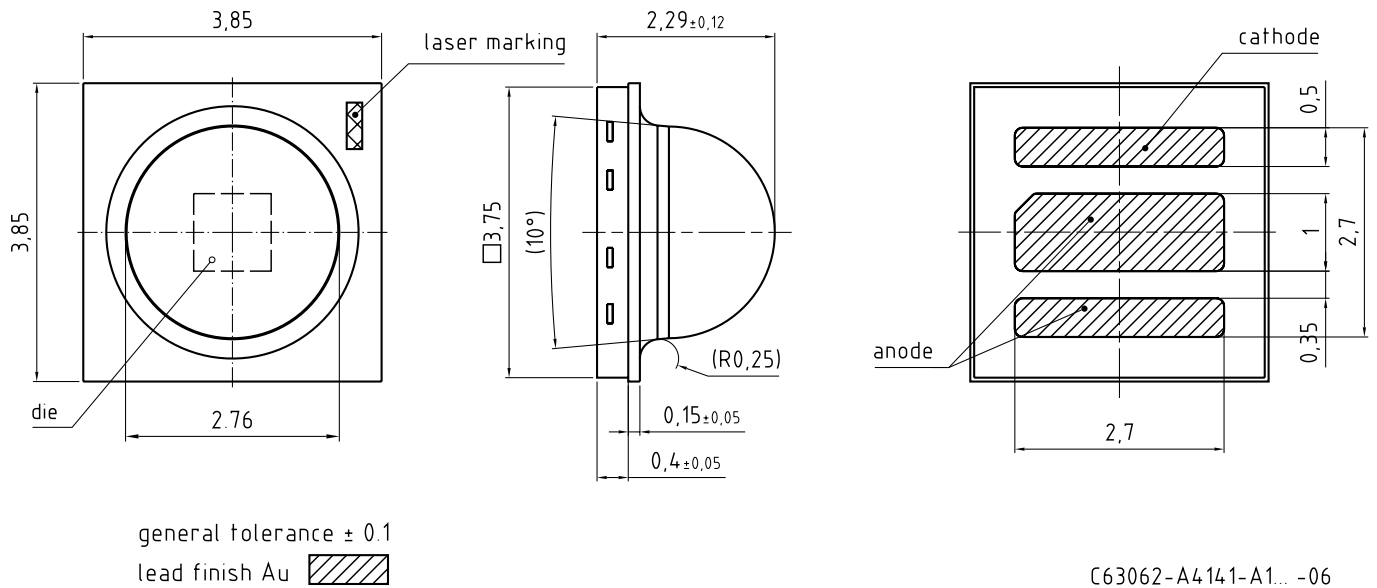


Permissible Pulse Handling Capability

$$I_F = f(t_p); D = \text{parameter}; T_S = 85^\circ C$$



Dimensional Drawing ⁹⁾



Further Information:

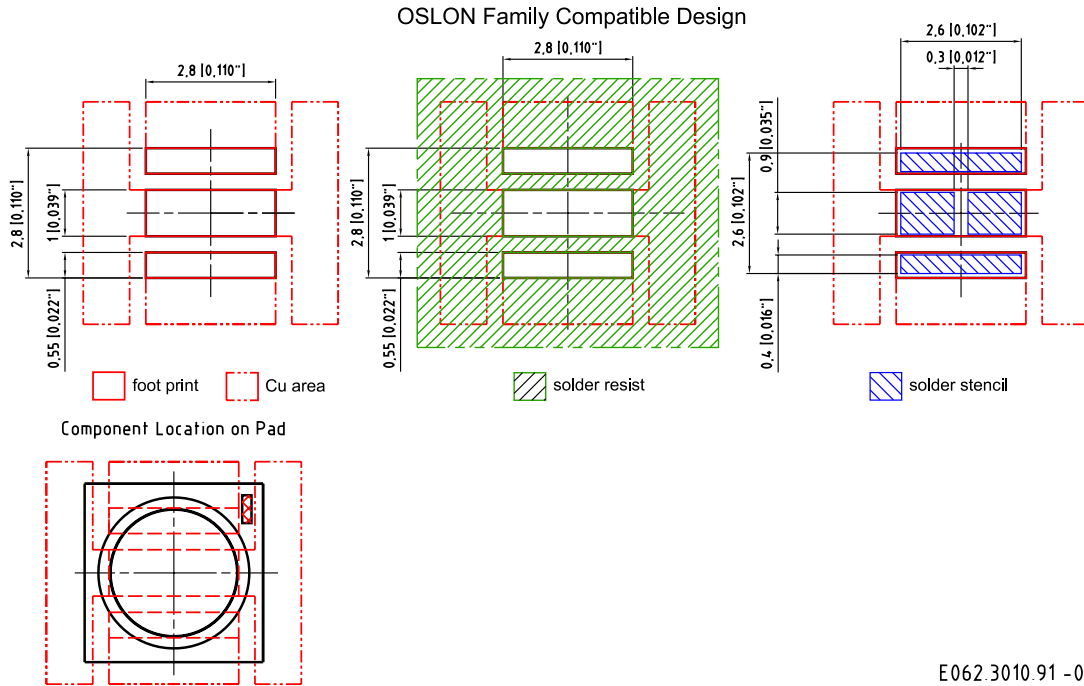
Approximate Weight: 31.0 mg

Package marking: Cathode

Corrosion test: Class: 3B
 Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC 60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

Recommended Solder Pad ⁹⁾



E062.3010.91-05

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

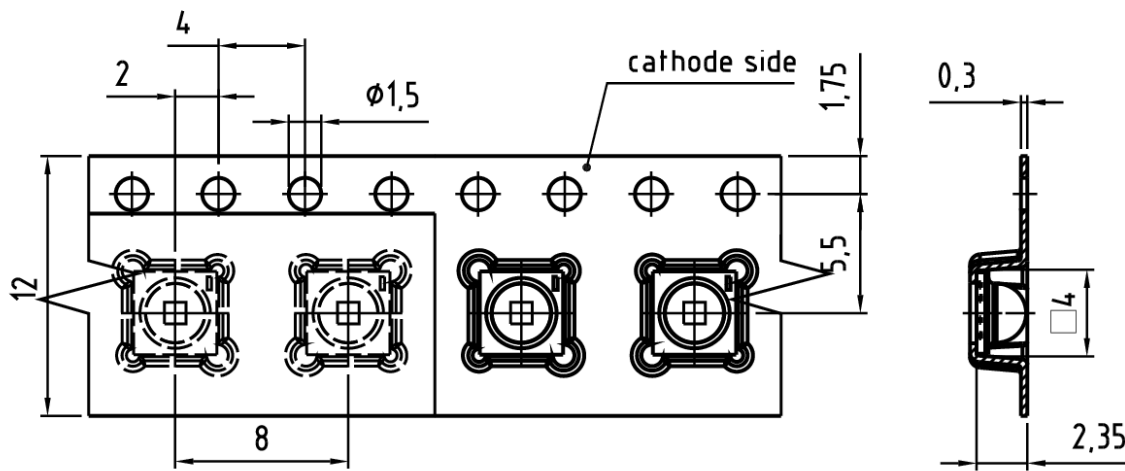


| Profile Feature | Symbol | Pb-Free (SnAgCu) Assembly | | | Unit |
|--|--------|---------------------------|----------------|---------|------|
| | | Minimum | Recommendation | Maximum | |
| Ramp-up rate to preheat ^{*)} 25 °C to 150 °C | | | 2 | 3 | K/s |
| Time t_s T_{Smin} to T_{Smax} | t_s | 60 | 100 | 120 | s |
| Ramp-up rate to peak ^{*)} T_{Smax} to T_p | | | 2 | 3 | K/s |
| Liquidus temperature | T_L | | 217 | | °C |
| Time above liquidus temperature | t_L | | 80 | 100 | s |
| Peak temperature | T_p | | 245 | 260 | °C |
| Time within 5 °C of the specified peak temperature $T_p - 5$ K | t_p | 10 | 20 | 30 | s |
| Ramp-down rate* T_p to 100 °C | | | 3 | 6 | K/s |
| Time 25 °C to T_p | | | | 480 | s |

All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping ⁹⁾



C63062-A4141-B8 -02

Tape and Reel ¹⁰⁾



Reel Dimensions

| A | W | N_{\min} | W_1 | $W_{2\max}$ | Pieces per PU |
|--------|---------------------|------------|-------------|-------------|---------------|
| 180 mm | 12 + 0.3 / - 0.1 mm | 60 mm | 12.4 + 2 mm | 18.4 mm | 600 |
| 330 mm | 12 + 0.3 / - 0.1 mm | 60 mm | 12.4 + 2 mm | 18.4 mm | 3000 |

Barcode-Product-Label (BPL)

OSRAM Opto Semiconductors LX XXXX BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890

(1T) LOT NO: 1234567890 (9D) D/C: 1234

(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

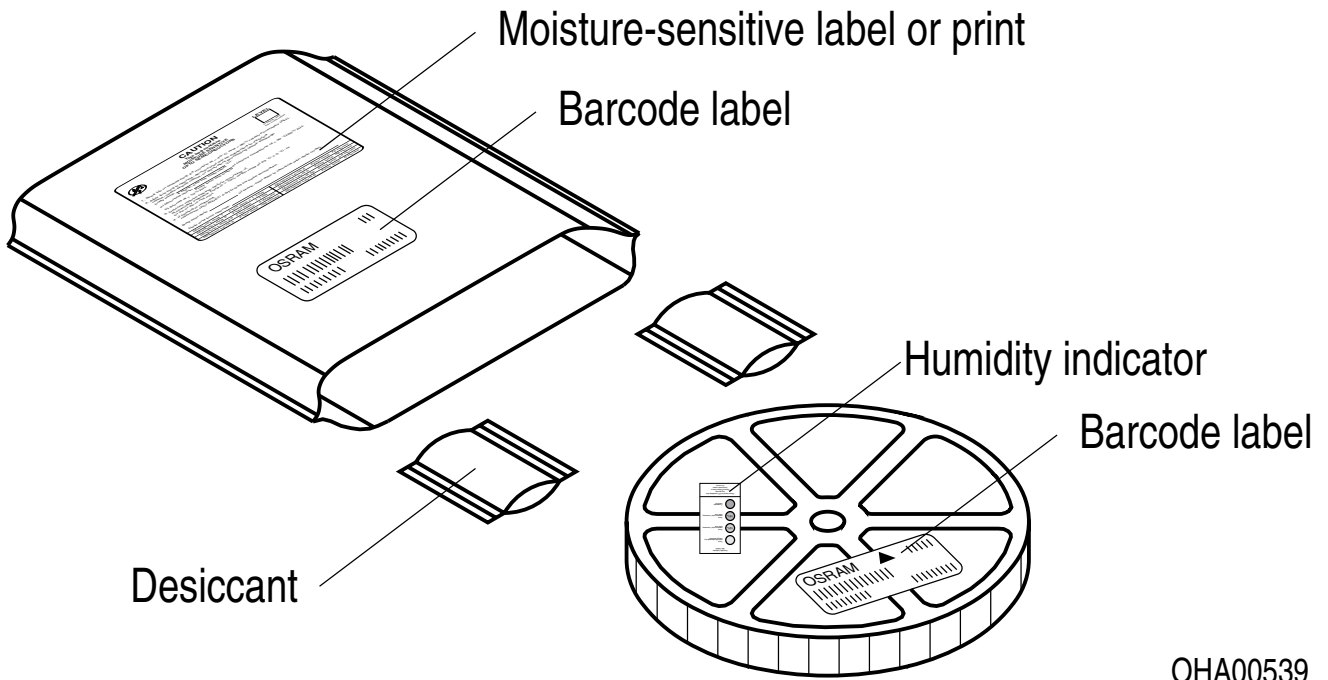
ML Temp ST
X XXX °C X

Pack: RXX
DEMY XXX
X_X123_1234.1234 X

The diagram shows a rectangular label with rounded corners. It contains the OSRAM logo and product name at the top left. To the right are fields for 'LX XXXX' and 'BIN1: XX-XX-X-XXX-X'. Below the logo is a 'RoHS Compliant' statement. The label features three horizontal barcode areas. The first is labeled '(6P) BATCH NO: 1234567890'. The second is labeled '(1T) LOT NO: 1234567890' and '(9D) D/C: 1234'. The third is labeled '(X) PROD NO: 123456789(Q)QTY: 9999' and '(G) GROUP: XX-XX-X-X'. To the right of the second barcode is a 'no liquid' symbol (a circle with a diagonal line and three droplets) and the text 'ML Temp ST X XXX °C X'. Below this is a square QR code. Further down is the text 'Pack: RXX', 'DEMY XXX', and 'X_X123_1234.1234 X'. A large, semi-transparent 'EXAMPLE' watermark is overlaid diagonally across the center of the label.

OHA04563

Dry Packing Process and Materials ⁹⁾



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

- 1) **Radiant intensity:** Measured at a solid angle of $\Omega = 0.01$ sr
- 2) **Brightness:** The brightness values are measured with a tolerance of $\pm 11\%$.
- 3) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- 4) **Forward Voltage:** The forward voltages are measured with a tolerance of ± 0.1 V.
- 5) **Total radiant flux:** Measured with integrating sphere.
- 6) **Thermal resistance:** junction - soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- 7) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 8) **Testing temperature:** $T_A = 25^\circ\text{C}$ (unless otherwise specified)
- 9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

| Version | Date | Change |
|---------|------------|--|
| 1.0 | 2019-09-05 | Initial Version |
| 1.1 | 2020-08-26 | Schematic Transportation Box Dimensions of Transportation Box |
| 1.2 | 2021-04-09 | Ordering Information Reel Dimensions |
